











**INA186** 

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# INA186 双向、低功耗、零漂移、宽动态范围 电流检测放大器

## 1 特性

- 低功耗:
  - 低电源电压 (Vs): 1.7V 至 5.5V
  - 低静态电流 (I<sub>O</sub>): 48μA (典型值)
- 低输入偏置电流 (I<sub>IB</sub>): 500pA (典型值) (支持微安级电流测量)
- 双向电流检测功能
- 精度:
  - 增益误差 (E<sub>G</sub>): ±1%(最大值)
  - 增益漂移: 10ppm/°C(最大值)
  - 失调电压 (V<sub>OS</sub>): ±50μV (最大值)
  - 温漂: 0.5μV/°C (最大值)
- 宽共模电压范围 (V<sub>CM</sub>): -0.2V 至 +40V
- 增益选项:
  - INA186A1: 25V/V
  - INA186A2: 50V/V
  - INA186A3: 100V/V
  - INA186A4: 200V/V
  - INA186A5: 500V/V

## 2 应用

- 笔记本电脑
- 手机。
- 电池供电设备
- 电信设备
- 电源管理
- 电池充电器

## 3 说明

INA186 是一款双向、低功耗的电压输出、电流检测放大器(也称为电流分流监控器)。此器件常用于过流保护、针对系统优化的精密电流测量或闭环反馈电路。

INA186 可在独立于电源电压的 -0.2V 至 +40V 共模电压下检测分流器上的压降。提供了五个固定增益选项: 25V/V、50V/V、100V/V、200V/V 或 500V/V。

INA186 的低输入偏置电流允许使用较大的电流检测电阻器,从而能够提供微安级的精确电流测量。零漂移架构的低失调电压扩展了电流测量的动态范围。此功能可支持较小的感应电阻器在具有较低功率损耗的同时,仍提供精确的电流测量。

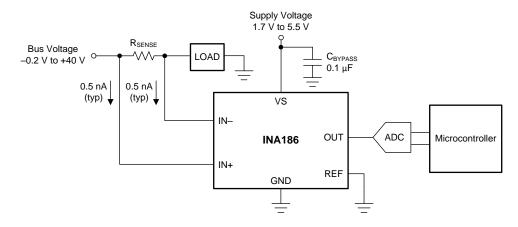
INA186 由  $1.7V \, \Xi \, 5.5V \,$  单电源供电,在启用时消耗的最大电源电流为  $90\mu A$ 。该器件的额定工作温度范围为  $-40^{\circ}C \, \Xi \, +125^{\circ}C$ ,并且采用 SC70 封装。

## 器件信息<sup>(1)</sup>

器件型号	封装	封装尺寸 (标称值)
INA186	SC70 (6)	2.00mm × 1.25mm

(1) 如需了解所有可用封装,请参阅数据表末尾的封装选项附录。

## 简化原理图







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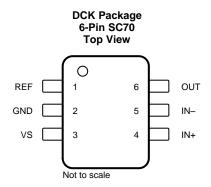
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# 4 修订历史记录

日期	修订版本	说明
2019 年2 月	*	初始发行版。



# **5 Pin Configuration and Functions**



## **Pin Functions**

PIN		TYPE	DESCRIPTION			
NAME	NAME NO.		DESCRIPTION			
GND	2	Analog	Ground			
IN-	5	Analog input	Current-sense amplifier negative input. For high-side applications, connect to load side of sense resistor. For low-side applications, connect to ground side of sense resistor.			
IN+	4	Analog input	Current-sense amplifier positive input. For high-side applications, connect to bus voltage side of sense resistor. For low-side applications, connect to load side of sense resistor.			
OUT	6	Analog output	OUT pin. This pin provides an analog voltage output that is the gained up voltage difference from the IN+ to the IN- pins, and is offset by the voltage applied to the REF pin.			
REF	1	Analog input	Reference input. Enables bidirectional current sensing with an externally applied voltage.			
VS	3	Analog	Power supply, 1.7 V to 5.5 V			

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## 6 Specifications

## 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT	
V <sub>S</sub>	Supply voltage			6	V	
	Analog inputs V V (2)	Differential $(V_{IN+}) - (V_{IN-})$		42	V	
	Analog inputs, V <sub>IN+</sub> , V <sub>IN-</sub> <sup>(2)</sup>	V <sub>IN+</sub> , V <sub>IN-</sub> , with respect to GND <sup>(3)</sup>	GND - 0.3	42	V	
	REF, OUT <sup>(3)</sup>		GND - 0.3	$(V_S) + 0.3$	V	
	Input current into any pin (3)			5	mA	
T <sub>A</sub>	Operating temperature		-55	150	°C	
TJ	Junction temperature	_		150	°C	
$T_{stg}$	Storage temperature		-65	150	°C	

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2)  $V_{IN+}$  and  $V_{IN-}$  are the voltages at the IN+ and IN- pins, respectively.

## 6.2 ESD Ratings

			VALUE	UNIT	
V Electrostatic discharge		Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>		\/	
V <sub>(ESD)</sub>	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 (2)	±1000	V	

<sup>(1)</sup> JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

## 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM MAX	UNIT
V <sub>CM</sub>	Common-mode input range	GND - 0.2	40	V
V <sub>IN+</sub> , V <sub>IN-</sub>	Input pin voltage range	GND - 0.2	40	V
Vs	Operating supply voltage	1.7	5.5	V
V <sub>REF</sub>	Reference pin voltage range	GND	Vs	V
T <sub>A</sub>	Operating free-air temperature	-40	125	°C

#### 6.4 Thermal Information

		INA186	
	THERMAL METRIC <sup>(1)</sup>	DCK (SC70)	UNIT
		6 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	170.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	132.7	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	65.3	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	45.7	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	65.2	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

ISTRUMENTS

<sup>(3)</sup> Input voltage at any pin may exceed the voltage shown if the current at that pin is limited to 5 mA.

<sup>(2)</sup> JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.



## 6.5 Electrical Characteristics

at  $T_A = 25$  °C,  $V_{SENSE} = V_{IN+} - V_{IN-}$ ,  $V_S = 1.8$  V to 5.0 V,  $V_{IN+} = 12$  V, and  $V_{REF} = V_S$  / 2 (unless otherwise noted)

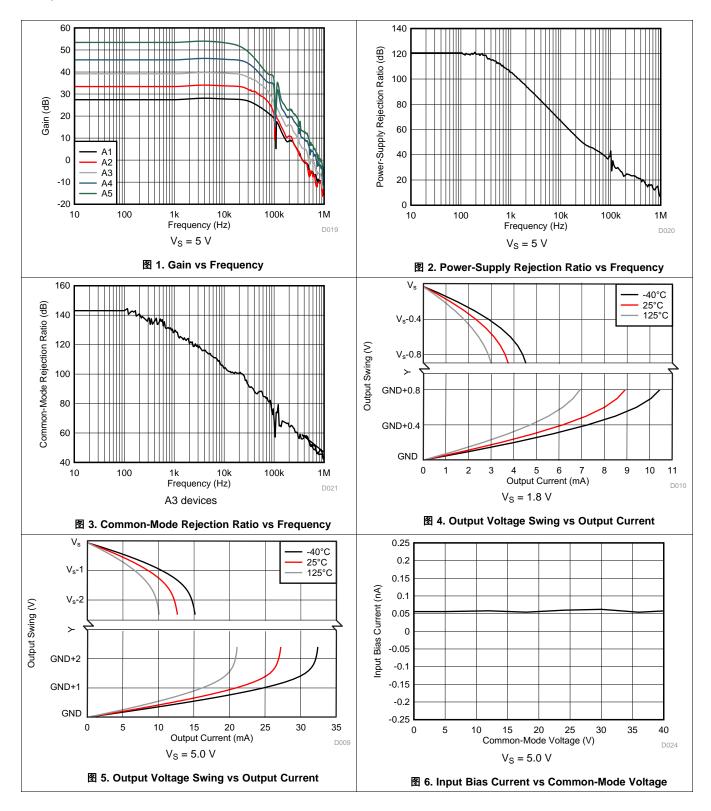
	PARAMETER	CONDITIONS	MIN TYP	MAX	UNIT
INPUT					
CMRR	Common-mode rejection ratio	V <sub>SENSE</sub> = 0 mV, V <sub>IN+</sub> = -0.1 V to 40 V, T <sub>A</sub> = -40°C to +125°C	120 150		dB
Vos	Offset voltage, RTI <sup>(1)</sup>	$V_S = 1.8 \text{ V}, V_{SENSE} = 0 \text{ mV}$	-3	±50	μV
dV <sub>OS</sub> /dT	Offset drift, RTI	$V_{SENSE} = 0 \text{ mV}, T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	0.05	0.5	μV/°C
PSRR	Power-supply rejection ratio, RTI	V <sub>SENSE</sub> = 0 mV, V <sub>S</sub> = 1.7 V to 5.5 V	-1	±10	μV/V
$I_{IB}$	Input bias current	V <sub>SENSE</sub> = 0 mV	0.5	3	nA
I <sub>IO</sub>	Input offset current	V <sub>SENSE</sub> = 0 mV	±0.07		nA
OUTPUT					
		A1 devices	25		
		A2 devices	50		
G	Gain	A3 devices	100		V/V
		A4 devices	200		
		A5 devices	500		
E <sub>G</sub>	Gain error	V <sub>OUT</sub> = 0.1 V to V <sub>S</sub> - 0.1 V	-0.04%	±1%	
	Gain error drift	$T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	2	10	ppm/°C
	Nonlinearity error	$V_{OUT} = 0.1 \text{ V to } V_S - 0.1 \text{ V}$	±0.01%		
RVRR	Reference voltage rejection ratio	$V_{REF} = 100 \text{ mV to } V_{S} - 100 \text{ mV},$ $T_{A} = -40^{\circ}\text{C to } +125^{\circ}\text{C}$	±2	±10	μV/V
	Maximum capacitive load	No sustained oscillation	1		nF
VOLTAGE	E OUTPUT				!
$V_{SP}$	Swing to V <sub>S</sub> power- supply rail	$V_S$ = 1.8 V, $R_L$ = 10 k $\Omega$ to GND, $T_A$ = -40°C to +125°C	(V <sub>S</sub> ) – 20	(V <sub>S</sub> ) - 40	mV
V <sub>SN</sub>	Swing to GND	$V_S$ = 1.8 V, $R_L$ = 10 k $\Omega$ to GND, $T_A$ = -40°C to +125°C, $V_{SENSE}$ = -10 mV, $V_{REF}$ = 0 V	(V <sub>GND</sub> ) + 0.05	(V <sub>GND</sub> ) + 1	mV
$V_{ZL}$	Zero current output voltage	$V_S$ = 1.8 V, $R_L$ = 10 k $\Omega$ to GND, $T_A$ = -40°C to +125°C, $V_{SENSE}$ = 0 mV, $V_{REF}$ = 0 V	(V <sub>GND</sub> ) + 2	(V <sub>GND</sub> ) + 10	mV
FREQUE	NCY RESPONSE				
		A1 devices, C <sub>LOAD</sub> = 10 pF	45		
		A2 devices, C <sub>LOAD</sub> = 10 pF	37		
BW	Bandwidth	A3 devices, C <sub>LOAD</sub> = 10 pF	35		kHz
		A4 devices, C <sub>LOAD</sub> = 10 pF	33		
		A5 devices, C <sub>LOAD</sub> = 10 pF	27		
SR	Slew rate	V <sub>S</sub> = 5.0 V, V <sub>OUT</sub> = 0.5 V to 4.5 V	0.3		V/µs
t <sub>S</sub>	Settling time	From current step to within 1% of final value	30		μs
NOISE, R	TI <sup>(1)</sup>	·			
	Voltage noise density		75		nV/√ <del>Hz</del>
POWER S	SUPPLY	,			
	0.1	V <sub>S</sub> = 1.8 V, V <sub>SENSE</sub> = 0 mV	48	65	μΑ
IQ	Quiescent current	$V_S = 1.8 \text{ V}, V_{SENSE} = 0 \text{ mV}, T_A = -40^{\circ}\text{C to } +125^{\circ}\text{C}$		90	μΑ

<sup>(1)</sup> RTI = referred-to-input.

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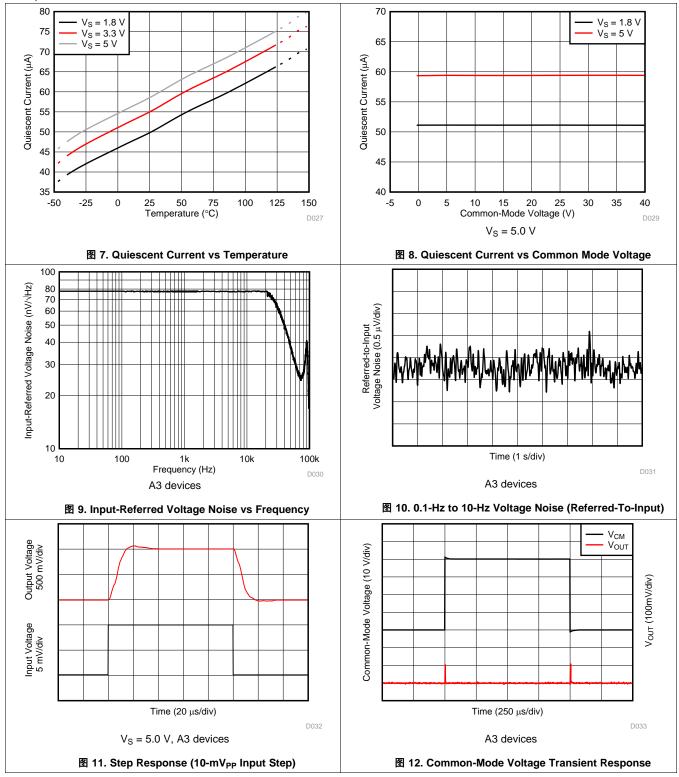
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## 6.6 Typical Characteristics





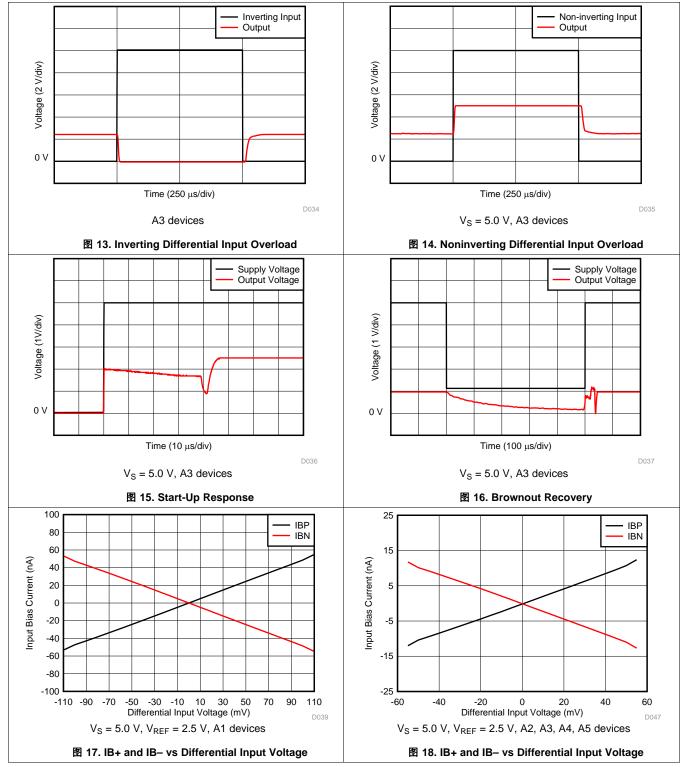
# Typical Characteristics (接下页)





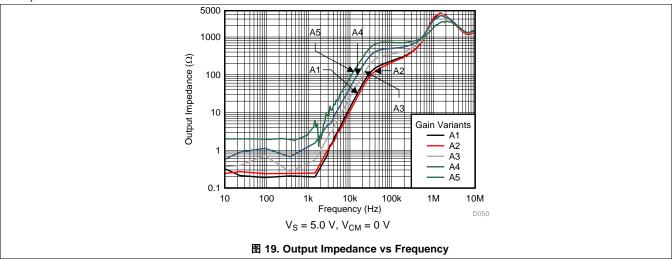
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## Typical Characteristics (接下页)





## Typical Characteristics (接下页)



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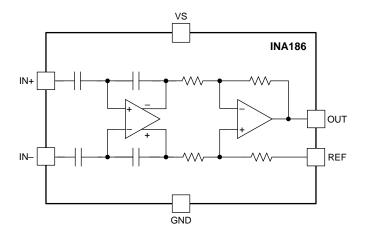
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## 7 Detailed Description

## 7.1 Overview

The INA186 is a low bias current, low offset, 40-V common-mode, current-sensing amplifier. The INA186 is a specially designed, current-sensing amplifier that accurately measures voltages developed across current-sensing resistors on common-mode voltages that far exceed the supply voltage. Current is measured on input voltage rails as high as 40 V at  $V_{\text{IN}+}$  and  $V_{\text{IN}-}$ , with a supply voltage,  $V_{\text{S}}$ , as low as 1.7 V. The INA186 is intended for use in both low-side and high-side current-sensing configurations where high accuracy and low current consumption are required.

## 7.2 Functional Block Diagram





7.3 Feature Description

#### 7.3.1 Precision Current Measurement

The INA186 allows for accurate current measurements over a wide dynamic range. The high accuracy of the device is attributable to the low gain error and offset specifications. The offset voltage of the INA186 is less than  $\pm 50~\mu V$ . In this case, the low offset improves the accuracy at light loads when  $V_{IN+}$  approaches  $V_{IN-}$ . Another advantage of low offset is the ability to use a lower-value shunt resistor that reduces the power loss in the current-sense circuit, and improves the power efficiency of the end application.

The maximum gain error of the INA186 is specified at  $\pm 1\%$ . As the sensed voltage becomes much larger than the offset voltage, the gain error becomes the dominant source of error in the current-sense measurement. When the device monitors currents near the full-scale output range, the total measurement error approaches the value of the gain error.

#### 7.3.2 Low Input Bias Current

The INA186 is different from many current-sense amplifiers because this device offers very low input bias current. The low input bias current of the INA186 has three primary benefits.

The first benefit is the reduction of the current consumed by the device. Classical current-sense amplifier topologies typically consume tens of microamps of current at the inputs. For these amplifiers, the input current is the result of the resistor network that sets the gain and additional current to bias the input amplifier. To reduce the bias current to near zero, the INA186 uses a capacitively coupled amplifier on the input stage, followed by a difference amplifier on the output stage.

The second benefit of low bias current is the ability to use input filters to reject high-frequency noise before the signal is amplified. In a traditional current-sense amplifier, the addition of input filters comes at the cost of reduced accuracy. However, as a result of the low bias currents, input filters have little effect on the measurement accuracy of the INA186.

The third benefit of low bias current is the ability to use a larger current-sense resistor. This ability allows the device to accurately monitor currents as low as 1 µA.

#### 7.3.3 Low Quiescent Current

The device features low quiescent current ( $I_Q$ ), while still providing sufficient small-signal bandwidth to be usable in most applications. The quiescent current of the INA186 is only 48  $\mu$ A (typ), while providing a small-signal bandwidth of 35 kHz in a gain of 100. The low  $I_Q$  and good bandwidth allow the device to be used in many portable electronic systems without excessive drain on the battery.

#### 7.3.4 Bidirectional Current Monitoring

INA186 devices can sense current flow through a sense resistor in both directions. The bidirectional current-sensing capability is achieved by applying a voltage at the REF pin to offset the output voltage. A positive differential voltage sensed at the inputs results in an output voltage that is greater than the applied reference voltage. Likewise, a negative differential voltage at the inputs results in output voltage that is less than the applied reference voltage. The output voltage of the current-sense amplifier is shown in 公式 1.

$$V_{OUT} = (I_{LOAD} \times R_{SENSE} \times GAIN) + V_{REF}$$

where

- I<sub>LOAD</sub> is the load current to be monitored.
- R<sub>SENSE</sub> is the current-sense resistor.
- GAIN is the gain option of the selected device.
- V<sub>REF</sub> is the voltage applied to the REF pin.

(1)



## Feature Description (接下页)

#### 7.3.5 High-Side and Low-Side Current Sensing

The INA186 supports input common-mode voltages from -0.2 V to +40 V. Because of the internal topology, the common-mode range is not restricted by the power-supply voltage ( $V_S$ ). The ability to operate with common-mode voltages greater or less than  $V_S$  allows the INA186 to be used in high-side and low-side current-sensing applications, as shown in 20.

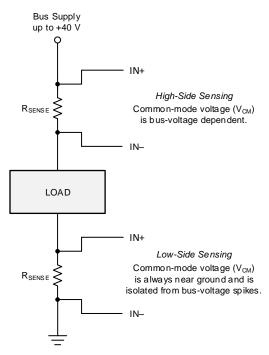


图 20. High-Side and Low-Side Sensing Connections

## 7.3.6 High Common-Mode Rejection

The INA186 uses a capacitively coupled amplifier on the front end. Therefore, dc common-mode voltages are blocked from downstream circuits, resulting in very high common-mode rejection. Typically, the common-mode rejection of the INA186 is approximately 150 dB. The ability to reject changes in the dc common-mode voltage allows the INA186 to monitor both high-voltage and low-voltage rail currents with very little change in the offset voltage.

#### 7.3.7 Rail-to-Rail Output Swing

The INA1860 allows linear current-sensing operation with the output close to the supply rail and ground. The maximum specified output swing to the positive rail is  $V_S - 40$  mV, and the maximum specified output swing to GND is only GND + 1 mV. The close-to-rail output swing is useful to maximize the usable output range, particularly when operating the device from a 1.8-V supply.



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#### Device Functional Modes

#### 7.4.1 Normal Operation

The INA186 is in normal operation when the following conditions are met:

- The power-supply voltage (V<sub>S</sub>) is between 1.7 V and 5.5 V.
- The common-mode voltage  $(V_{CM})$  is within the specified range of -0.2 V to +40 V.
- The maximum differential input signal times the gain plus V<sub>REF</sub> is less than the positive swing voltage V<sub>SP</sub>.
- The minimum differential input signal times the gain plus V<sub>REF</sub> is greater than the zero load swing to GND, V<sub>ZI</sub> (see the Rail-to-Rail Output Swing section).

During normal operation, this device produces an output voltage that is the amplified representation of the difference voltage from IN+ to IN- plus the voltage applied to the REF pin.

#### 7.4.2 Unidirectional Mode

This device can be configured to monitor current flowing in one direction (unidirectional) or in both directions (bidirectional) depending on how the REF pin is connected. The most common case is unidirectional where the output is set to ground when no current is flowing by connecting the REF pin to ground, as shown in 🗵 21. When the current flows from the bus supply to the load, the input voltage from IN+ to IN- increases and causes the output voltage at the OUT pin to increase.

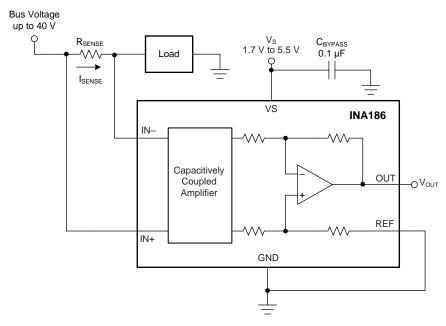


图 21. Typical Unidirectional Application

The linear range of the output stage is limited by how close the output voltage can approach ground under zero input conditions. The zero current output voltage of the INA186 is very small and for most unidirectional applications the REF pin is simply grounded. However, if the measured current multiplied by the current sense resistor and device gain is less than the zero current output voltage, then bias the REF pin to a convenient value above the zero current output voltage to get the output into the linear range of the device. To limit common-mode rejection errors, buffer the reference voltage connected to the REF pin.

A less-frequently used output biasing method is to connect the REF pin to the power-supply voltage, V<sub>S</sub>. This method results in the output voltage saturating at 40 mV less than the supply voltage when no differential input voltage is present. This method is similar to the output saturated low condition with no differential input voltage when the REF pin is connected to ground. The output voltage in this configuration only responds to currents that develop negative differential input voltage relative to the device IN- pin. Under these conditions, when the negative differential input signal increases, the output voltage moves downward from the saturated supply voltage. The voltage applied to the REF pin must not exceed V<sub>S</sub>.



## Device Functional Modes (接下页)

Another use for the REF pin in unidirectional operation is to level shift the output voltage. 

22 shows an application where the device ground is set to a negative voltage so currents biased to negative supplies, as seen in optical networking cards, can be measured. The GND of the INA186 can be set to negative voltages, as long as the inputs do not violate the common-mode range specification and the voltage difference between VS and GND does not exceed 5.5 V. In this example, the output of the INA186 is fed into a positive-biased analog-to-digital converter (ADC). By grounding the REF pin, the voltages at the output will be positive and not damage the ADC. To make sure the output voltage never goes negative, the supply sequencing must be the positive supply first, followed by the negative supply.

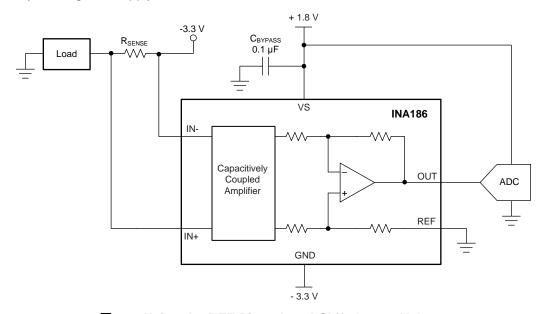


图 22. Using the REF Pin to Level-Shift Output Voltage



Device Functional Modes (接下页)

#### 7.4.3 Bidirectional Mode

The INA186 is a bidirectional current-sense amplifier capable of measuring currents through a resistive shunt in two directions. This bidirectional monitoring is common in applications that include charging and discharging operations where the current flowing through the resistor can change directions.

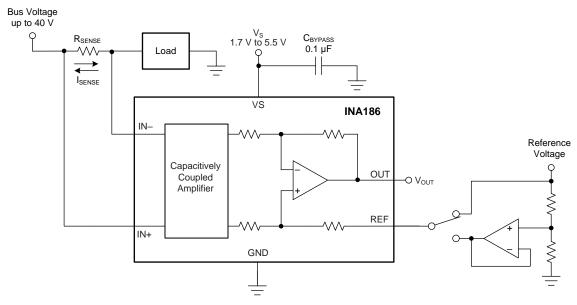


图 23. Bidirectional Application

The ability to measure this current flowing in both directions is achieved by applying a voltage to the REF pin, as shown in 23. The voltage applied to REF ( $V_{REF}$ ) sets the output state that corresponds to the zero-input level state. The output then responds by increasing above  $V_{REF}$  for positive differential signals (relative to the IN– pin) and responds by decreasing below  $V_{REF}$  for negative differential signals. This reference voltage applied to the REF pin can be set anywhere between 0 V to  $V_{S}$ . For bidirectional applications,  $V_{REF}$  is typically set at  $V_{S}/2$  for equal signal range in both current directions. In some cases,  $V_{REF}$  is set at a voltage other than  $V_{S}/2$ ; for example, when the bidirectional current and corresponding output signal do not need to be symmetrical.

## 7.4.4 Input Differential Overload

If the differential input voltage ( $V_{\text{IN+}} - V_{\text{IN-}}$ ) times gain exceeds the voltage swing specification, the INA186 drives its output as close as possible to the positive supply or ground, and does not provide accurate measurement of the differential input voltage. If this input overload occurs during normal circuit operation, then reduce the value of the shunt resistor or use a lower-gain version with the chosen sense resistor to avoid this mode of operation. If a differential overload occurs in a time-limited fault event, then the output of the INA186 returns to the expected value approximately 80  $\mu$ s after the fault condition is removed.

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## 8 Application and Implementation

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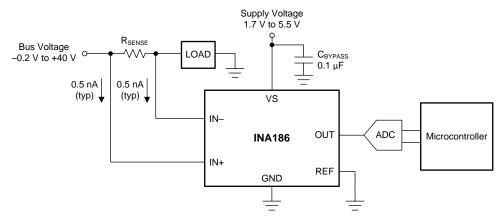
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

## 8.1 Application Information

The INA186 amplifies the voltage developed across a current-sensing resistor as current flows through the resistor to the load or ground. The high common-mode rejection of the INA186 makes it usable over a wide range of voltage rails while still maintaining an accurate current measurement.

#### 8.1.1 Basic Connections

⊠ 24 shows the basic connections of the INA186. Place the device as close as possible to the current sense resistor and connect the input pins (IN+ and IN−) to the current sense resistor through kelvin connections.



NOTE: To help eliminate ground offset errors between the device and the analog-to-digital converter (ADC), connect the REF pin to the ADC reference input. When driving SAR ADCs, filter or buffer the output of the INA186 before connecting directly to the ADC.

图 24. Basic Connections

(2)

(3)

(4)

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## Application Information (接下页)

## 8.1.2 R<sub>SENSE</sub> and Device Gain Selection

The accuracy of any current-sense amplifier is maximized by choosing the current-sense resistor to be as large as possible. A large sense resistor maximizes the differential input signal for a given amount of current flow and reduces the error contribution of the offset voltage. However, there are practical limits as to how large the current-sense resistor can be in a given application because of the resistor size and maximum allowable power dissipation. 公式 2 gives the maximum value for the current-sense resistor for a given power dissipation budget:

$$R_{SENSE} < \frac{PD_{MAX}}{{I_{MAX}}^2}$$

#### where:

- PD<sub>MAX</sub> is the maximum allowable power dissipation in R<sub>SENSE</sub>.
- I<sub>MAX</sub> is the maximum current that will flow through R<sub>SENSE</sub>.

An additional limitation on the size of the current-sense resistor and device gain is due to the power-supply voltage, V<sub>S</sub>, and device swing-to-rail limitations. In order to make sure that the current-sense signal is properly passed to the output, both positive and negative output swing limitations must be examined. 公式 3 provides the maximum values of R<sub>SENSE</sub> and GAIN to keep the device from exceeding the positive swing limitation.

$$I_{MAX} \times R_{SENSE} \times GAIN < V_{SP} - V_{REF}$$

#### where:

- I<sub>MAX</sub> is the maximum current that will flow through R<sub>SENSE</sub>.
- GAIN is the gain of the current-sense amplifier.
- V<sub>SP</sub> is the positive output swing as specified in the data sheet.
- V<sub>REF</sub> is the externally applied voltage on the REF pin.

To avoid positive output swing limitations when selecting the value of R<sub>SENSE</sub>, there is always a trade-off between the value of the sense resistor and the gain of the device under consideration. If the sense resistor selected for the maximum power dissipation is too large, then it is possible to select a lower-gain device in order to avoid positive swing limitations.

The negative swing limitation places a limit on how small the sense resistor value can be for a given application. 公式 4 provides the limit on the minimum value of the sense resistor.

$$I_{MIN} \times R_{SENSE} \times GAIN > V_{SN} - V_{REF}$$

#### where:

- I<sub>MIN</sub> is the minimum current that will flow through R<sub>SENSE</sub>.
- GAIN is the gain of the current-sense amplifier.
- V<sub>SN</sub> is the negative output swing of the device (see Rail-to-Rail Output Swing).
- V<sub>REF</sub> is the externally applied voltage on the REF pin.

In addition to adjusting R<sub>SENSE</sub> and the device gain, the voltage applied to the REF pin can be slightly increased above GND to avoid negative swing limitations.



## Application Information (接下页)

## 8.1.3 Signal Conditioning

When performing accurate current measurements in noisy environments, the current-sensing signal is often filtered. The INA186 features low input bias currents. Therefore, adding a differential mode filter to the input without sacrificing the current-sense accuracy is possible. Filtering at the input is advantageous because this action attenuates differential noise before the signal is amplified. 图 25 provides an example of how to use a filter on the input pins of the device.

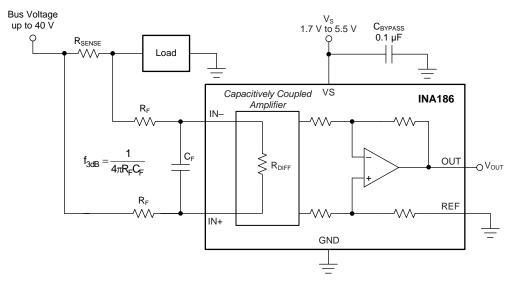


图 25. Filter at the Input Pins

The differential input impedance ( $R_{DIFF}$ ) shown in  $\boxtimes$  25 limits the maximum value for  $R_F$ . The value of  $R_{DIFF}$  is a function of the device temperature, as shown in  $\boxtimes$  26.

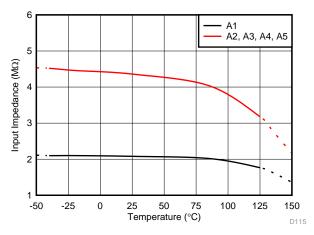


图 26. Differential Input Impedance vs Temperature



## Application Information (接下页)

As the voltage drop across the sense resistor ( $V_{SENSE}$ ) increases, the amount of voltage dropped across the input filter resistors ( $R_F$ ) also increases. The increased voltage drop results in additional gain error. The error caused by these resistors is calculated by the resistor divider equation shown in  $\Delta \pm 5$ .

Error(%) = 
$$\left(1 - \frac{R_{DIFF}}{R_{SENSE} + R_{DIFF} + (2 \times R_F)}\right) \times 100$$

where:

- R<sub>DIFF</sub> is the differential input impedance.
- R<sub>F</sub> is the added value of the series filter resistance.

(5)

The input stage of the INA186 uses a capacitive feedback amplifier topology in order to achieve high dc precision. As a result, periodic high-frequency shunt voltage (or current) transients of significant amplitude (10 mV or greater) and duration (hundreds of nanoseconds or greater) may be amplified by the INA186, even though the transients are greater than the device bandwidth. Use a differential input filter in these applications to minimize disturbances at the INA186 output.

The high input impedance and low bias current of the INA186 provides flexibility in the input filter design without impacting the accuracy of current measurement. For example, set  $R_F = 100~\Omega$  and  $C_F = 22~nF$  to achieve a low-pass filter corner frequency of 36.2 kHz. These filter values significantly attenuate most unwanted high-frequency signals at the input without severely impacting the current sensing bandwidth or precision. If a lower corner frequency is desired, increase the value of  $C_F$ .

Filtering the input filters out differential noise across the sense resistor. If high-frequency, common-mode noise is a concern, add an RC filter from the OUT pin to ground. The RC filter helps filter out both differential and common mode noise, as well as internally generated noise from the device. The value for the resistance of the RC filter is limited by the impedance of the load. Any current drawn by the load manifests as an external voltage drop from the INA186 OUT pin to the load input. To select the optimal values for the output filter, use 19 and see the Closed-Loop Analysis of Load-Induced Amplifier Stability Issues Using ZOUT application report

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## Application Information (接下页)

#### 8.1.4 Common-Mode Voltage Transients

With a small amount of additional circuitry, the INA186 can be used in circuits subject to transients that exceed the absolute maximum voltage ratings. The most simple way to protect the inputs from negative transients is to add resistors in series with the IN– and IN+ pins. Use resistors that are 1 k $\Omega$  or less, and limit the current in the ESD structures to less than 5 mA. For example, using 1-k $\Omega$  resistors in series with the INA186 allows voltages as low as –5 V, while limiting the ESD current to less than 5 mA. If protection from high-voltage or more-negative, common-voltage transients is needed, use the circuits shown in 27 and other implementing these circuits, use only Zener diodes or Zener-type transient absorbers (sometimes referred to as 27 and 27 a

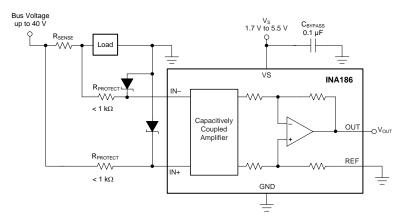


图 27. Transient Protection Using Dual Zener Diodes

In the event that low-power Zener diodes do not have sufficient transient absorption capability, a higher-power transzorb must be used. The most package-efficient solution involves using a single transzorb and back-to-back diodes between the device inputs, as shown in 图 28. The most space-efficient solutions are dual, series-connected diodes in a single SOT-523 or SOD-523 package. In either of the examples shown in 图 27 and 图 28, the total board area required by the INA186 with all protective components is less than that of an SO-8 package, and only slightly greater than that of an VSSOP-8 package.

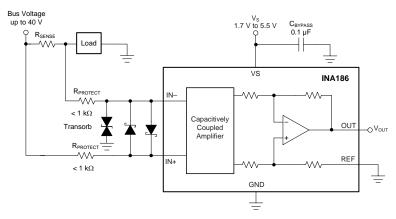


图 28. Transient Protection Using a Single Transzorb and Input Clamps

For more information, see the Current Shunt Monitor With Transient Robustness reference design.



## 8.2 Typical Applications

The low input bias current of the INA186 allows accurate monitoring of small-value currents. To accurately monitor currents in the microamp range, increase the value of the sense resistor to increase the sense voltage so that the error introduced by the offset voltage is small. The circuit configuration for monitoring low-value currents is shown in  $\ 29$ . As a result of the differential input impedance of the INA186, limit the value of  $R_{SENSE}$  to 1 k $\Omega$  or less for best accuracy.

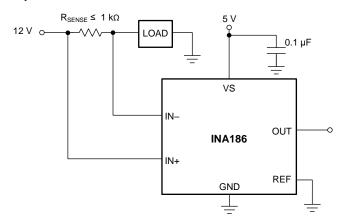


图 29. Microamp Current Measurement

## 8.2.1 Design Requirements

The design requirements for the circuit shown in 图 29 are listed in 表 1.

DESIGN PARAMETER	EXAMPLE VALUE
Power-supply voltage (V <sub>S</sub> )	5 V
Bus supply rail (V <sub>CM</sub> )	12 V
Minimum sense current (I <sub>MIN</sub> )	1 μΑ
Maximum sense current (I <sub>MAX</sub> )	150 μΑ
Device gain (GAIN)	25 V/V
Reference voltage (V <sub>REF</sub> )	0 V

表 1. Design Parameters

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# TEXAS INSTRUMENTS

#### 8.2.2 Detailed Design Procedure

The maximum value of the current-sense resistor is calculated based on choice of gain, value of the maximum current the be sensed ( $I_{MAX}$ ), and the power supply voltage ( $V_S$ ). When operating at the maximum current, the output voltage must not exceed the positive output swing specification,  $V_{SP}$ . Using  $\Delta \vec{\Xi}$  6, for the given design parameters the maximum value for  $R_{SENSE}$  is calculated to be 1.321 kΩ.

$$R_{SENSE} < \frac{V_{SP}}{I_{MAX} \times GAIN} \tag{6}$$

However, because this value exceeds the maximum recommended value for  $R_{SENSE}$ , a resistance value of 1 kΩ must be used. When operating at the minimum current value,  $I_{MIN}$  the output voltage must be greater than the swing to GND ( $V_{SN}$ ), specification. For this example, the output voltage at the minimum current is calculated using  $\Delta \vec{x}$  7 to be 25 mV, which is greater than the value for  $V_{SN}$ .

$$V_{OUTMIN} = I_{MIN} \times R_{SENSE} \times GAIN$$
(7)

## 8.2.3 Application Curve

图 30 shows the output of the device under the conditions given in 表 1 and with  $R_{SENSE} = 1 \text{ k}\Omega$ .

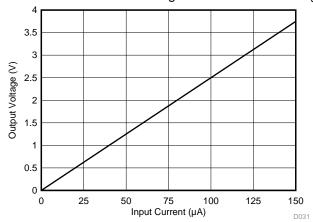


图 30. Typical Application DC Transfer Function



## 9 Power Supply Recommendations

The input circuitry of the INA186 accurately measures beyond the power-supply voltage,  $V_S$ . For example,  $V_S$  can be 5 V, whereas the bus supply voltage at IN+ and IN- can be as high as 40 V. However, the output voltage range of the OUT pin is limited by the voltage on the VS pin. The INA186 also withstands the full differential input signal range up to 40 V at the IN+ and IN- input pins, regardless of whether the device has power applied at the VS pin. There is no sequencing requirement for  $V_S$  and  $V_{IN+}$  or  $V_{IN-}$ .

## 10 Layout

## 10.1 Layout Guidelines

- Connect the input pins to the sensing resistor using a Kelvin or 4-wire connection. This connection technique
  makes sure that only the current-sensing resistor impedance is detected between the input pins. Poor routing
  of the current-sensing resistor commonly results in additional resistance present between the input pins.
  Given the very low ohmic value of the current resistor, any additional high-current carrying impedance can
  cause significant measurement errors.
- Place the power-supply bypass capacitor as close as possible to the device power supply and ground pins.
   The recommended value of this bypass capacitor is 0.1 μF. Additional decoupling capacitance can be added to compensate for noisy or high-impedance power supplies.
- When routing the connections from the current-sense resistor to the device, keep the trace lengths as short as possible. The input filter capacitor C<sub>F</sub> should be placed as close as possible to the input pins of the device.

## 10.2 Layout Example

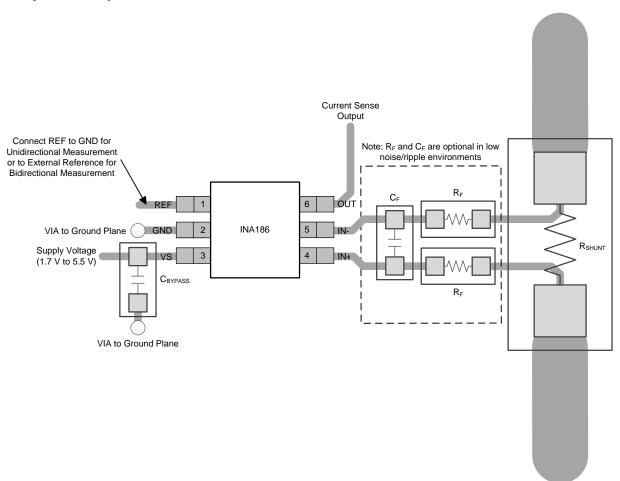


图 31. Recommended Layout for SC70 (DCK) Package

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# 11 器件和文档支持

#### 11.1 文档支持

#### 11.1.1 相关文档

请参阅如下相关文档:《INA186EVM 用户指南》

## 11.2 接收文档更新通知

要接收文档更新通知,请导航至 Tl.com.cn 上的器件产品文件夹。单击右上角的通知我 进行注册,即可每周接收产品信息更改摘要。有关更改的详细信息,请查看任何已修订文档中包含的修订历史记录。

## 11.3 社区资源

下列链接提供到 TI 社区资源的连接。链接的内容由各个分销商"按照原样"提供。这些内容并不构成 TI 技术规范,并且不一定反映 TI 的观点;请参阅 TI 的 《使用条款》。

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**ESD** 的损坏小至导致微小的性能降级,大至整个器件故障。 精密的集成电路可能更容易受到损坏,这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

## 11.6 术语表

#### SLYZ022 — TI 术语表。

这份术语表列出并解释术语、缩写和定义。

## 12 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更,恕不另行通知,且不会对此文档进行修订。如需获取此产品说明书的浏览器版本,请查阅左侧的导航栏。

INSTRUMENTS

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18-Apr-2019

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
INA186A1IDCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1E7	Samples
INA186A1IDCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1E7	Samples
INA186A2IDCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1E8	Samples
INA186A2IDCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1E8	Samples
INA186A3IDCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1E9	Samples
INA186A3IDCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1E9	Samples
INA186A4IDCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1EA	Samples
INA186A4IDCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1EA	Samples
INA186A5IDCKR	ACTIVE	SC70	DCK	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1EB	Samples
INA186A5IDCKT	ACTIVE	SC70	DCK	6	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1EB	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

<sup>(2)</sup> RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

<sup>(3)</sup> MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



## PACKAGE OPTION ADDENDUM

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- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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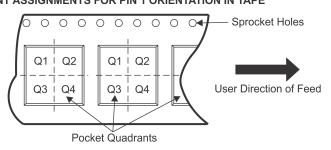
## TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

All difficultions are nominal			_									
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA186A1IDCKR	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
INA186A1IDCKT	SC70	DCK	6	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
INA186A2IDCKR	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
INA186A2IDCKT	SC70	DCK	6	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
INA186A3IDCKR	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
INA186A3IDCKT	SC70	DCK	6	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
INA186A4IDCKR	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
INA186A4IDCKT	SC70	DCK	6	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
INA186A5IDCKR	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
INA186A5IDCKT	SC70	DCK	6	250	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3

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\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA186A1IDCKR	SC70	DCK	6	3000	180.0	180.0	18.0
INA186A1IDCKT	SC70	DCK	6	250	180.0	180.0	18.0
INA186A2IDCKR	SC70	DCK	6	3000	180.0	180.0	18.0
INA186A2IDCKT	SC70	DCK	6	250	180.0	180.0	18.0
INA186A3IDCKR	SC70	DCK	6	3000	180.0	180.0	18.0
INA186A3IDCKT	SC70	DCK	6	250	180.0	180.0	18.0
INA186A4IDCKR	SC70	DCK	6	3000	180.0	180.0	18.0
INA186A4IDCKT	SC70	DCK	6	250	180.0	180.0	18.0
INA186A5IDCKR	SC70	DCK	6	3000	180.0	180.0	18.0
INA186A5IDCKT	SC70	DCK	6	250	180.0	180.0	18.0

# DCK (R-PDSO-G6)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
- D. Falls within JEDEC MO-203 variation AB.



# DCK (R-PDSO-G6)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- D. Publication IPC-7351 is recommended for alternate designs.
- E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.



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